



GPI testing board SMT IGBT on substrate

■ Motivations

- Testing of existing IGBT discrete SMT technologies on IMS substrates (DPak, D2Pak)
- Testing of new SMT packaging technologies (TO-LL, ThinPak, D3Pak)
- IGBT and SMT packaging benchmark vs competitors
- Improvement of conducted and Radiated EMI with embedded DC-Link capacitors on substrate and eventually output filters

• Main Features

- General Purpose Inverter testing board for discretized SMT IGBTs up to 10 Arms 230Vac.
- V_{in} 1- \emptyset 230Vac 50-60Hz
- V_{out} 230Vac variable speed 0Hz to 300Hz
- Switching frequency from 8kHz up to 30kHz
- IMS Substrate
- Embedded DC-Link
- XMC4400 microcontroller board with FOC.

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- 1HP Induction motor drive

